

Schematic Checklist for LAN89730

Information Particular for the 56-pin QFN Package

LAN89730 QFN Phy Interface:

1. TXP (pin 3); This pin is the transmit twisted pair output positive connection from the internal phy. It requires a 49.9Ω , 1.0% pull-up resistor to VDD33A (created from +3.3V). This pin also connects to the transmit channel of the magnetics.
2. TXN (pin 2); This pin is the transmit twisted pair output negative connection from the internal phy. It requires a 49.9Ω , 1.0% pull-up resistor to VDD33A (created from +3.3V). This pin also connects to the transmit channel of the magnetics.
3. For Transmit Channel connection and termination details, refer to Figure 1.
4. RXP (pin 6); This pin is the receive twisted pair input positive connection to the internal phy. It requires a 49.9Ω , 1.0% pull-up resistor to VDD33A (created from +3.3V). This pin also connects to the receive channel of the magnetics.
5. RXN (pin 5); This pin is the receive twisted pair input negative connection to the internal phy. It requires a 49.9Ω , 1.0% pull-up resistor to VDD33A (created from +3.3V). This pin also connects to the receive channel of the magnetics.
6. For Receive Channel connection and termination details, refer to Figure 2.



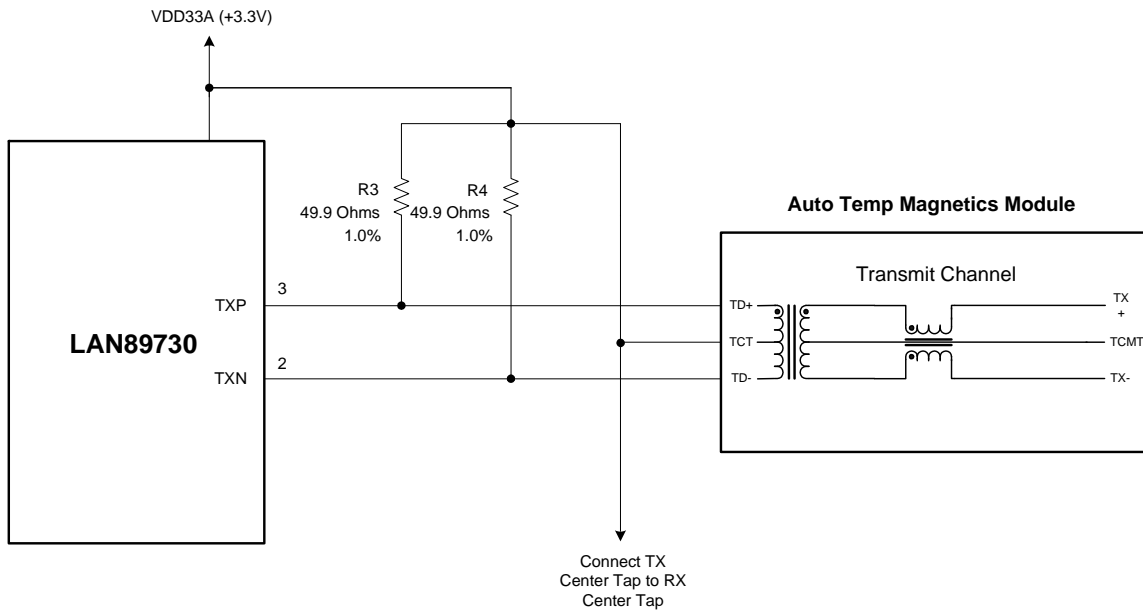


Figure 1 – Transmit Channel Connections and Terminations

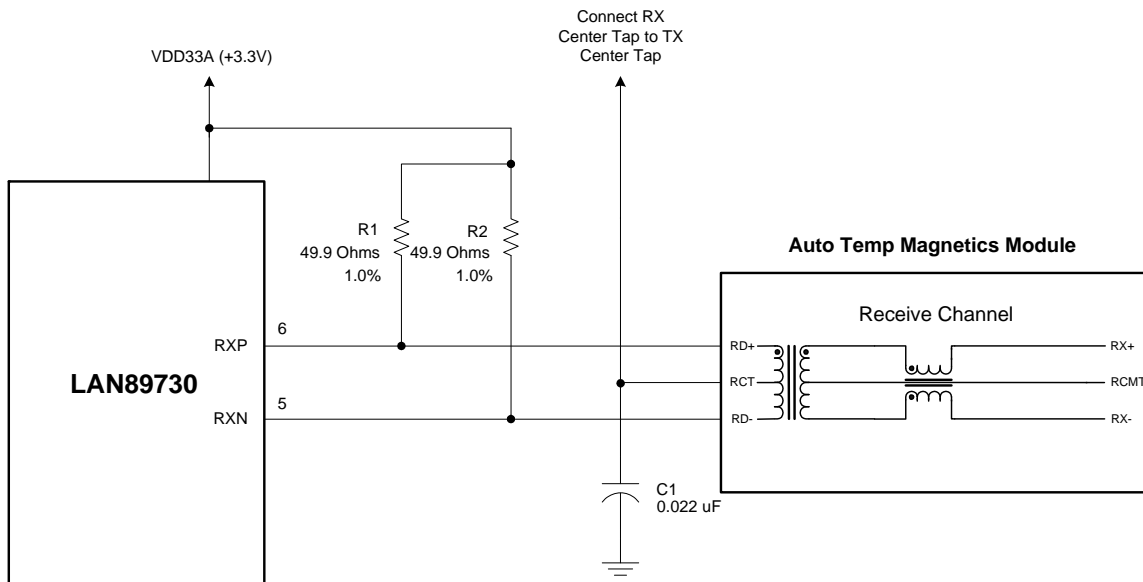


Figure 2 - Receive Channel Connections and Terminations

LAN89730 QFN Magnetics:

1. The center tap connection on the LAN89730 side for the transmit channel must be connected to VDDA (created from +3.3V) directly. The transmit channel center tap of the magnetics also connects to the receive channel center tap of the magnetics.
2. The center tap connection on the LAN89730 side for the receive channel is connected to the transmit channel center tap on the magnetics. In addition, a 0.022 μ F capacitor is required from the receive channel center tap of the magnetics to digital ground.
3. The center tap connection on the cable side (RJ45 side) for the transmit channel should be terminated with a 75 Ω resistor through a 1000 ρ F, 2KV capacitor ($C_{magterm}$) to chassis ground.
4. The center tap connection on the cable side (RJ45 side) for the receive channel should be terminated with a 75 Ω resistor through a 1000 ρ F, 2KV capacitor ($C_{magterm}$) to chassis ground.
5. Only one 1000 ρ F, 2KV capacitor ($C_{magterm}$) to chassis ground is required. It is shared by both TX & RX center taps.
6. Assuming the design of an end-point device (NIC), pin 1 of the RJ45 is TX+ and should trace through the magnetics to TXP (pin 3) of the LAN89730 QFN.
7. Assuming the design of an end-point device (NIC), pin 2 of the RJ45 is TX- and should trace through the magnetics to TXN (pin 2) of the LAN89730 QFN.
8. Assuming the design of an end-point device (NIC), pin 3 of the RJ45 is RX+ and should trace through the magnetics to RXP (pin 6) of the LAN89730 QFN.
9. Assuming the design of an end-point device (NIC), pin 6 of the RJ45 is RX- and should trace through the magnetics to RXN (pin 5) of the LAN89730 QFN.
10. When using the SMSC LAN89730 in the HP Auto MDIX mode of operation, the use of an Auto MDIX style magnetics module is required. Please refer to the SMSC Applications Note 8.13 "Suggested Magnetics" for proper magnetics.
11. In order to guarantee IEEE / AEC-Q100 compliancy over the entire temperature range of operation, the magnetics used in conjunction with the LAN89730 must be rated for Automotive Temperature use.



RJ45 Connector:

1. Pins 4 & 5 of the RJ45 connector connect to one pair of unused wires in CAT-5 type cables. These should be terminated to chassis ground through a 1000 ρ F, 2KV capacitor (C_{rjterm}). There are two methods of accomplishing this:
 - a) Pins 4 & 5 can be connected together with two 49.9 Ω resistors. The common connection of these resistors should be connected through a third 49.9 Ω to the 1000 ρ F, 2KV capacitor (C_{rjterm}).
 - b) For a lower component count, the resistors can be combined. The two 49.9 Ω resistors in parallel look like a 25 Ω resistor. The 25 Ω resistor in series with the 49.9 Ω makes the whole circuit look like a 75 Ω resistor. So, by shorting pins 4 & 5 together on the RJ45 and terminating them with a 75 Ω resistor in series with the 1000 ρ F, 2KV capacitor (C_{rjterm}) to chassis ground, creates an equivalent circuit.
2. Pins 7 & 8 of the RJ45 connector connect to one pair of unused wires in CAT-5 type cables. These should be terminated to chassis ground through a 1000 ρ F, 2KV capacitor (C_{rjterm}). There are two methods of accomplishing this:
 - a) Pins 7 & 8 can be connected together with two 49.9 Ω resistors. The common connection of these resistors should be connected through a third 49.9 Ω to the 1000 ρ F, 2KV capacitor (C_{rjterm}).
 - b) For a lower component count, the resistors can be combined. The two 49.9 Ω resistors in parallel look like a 25 Ω resistor. The 25 Ω resistor in series with the 49.9 Ω makes the whole circuit look like a 75 Ω resistor. So, by shorting pins 4 & 5 together on the RJ45 and terminating them with a 75 Ω resistor in series with the 1000 ρ F, 2KV capacitor (C_{rjterm}) to chassis ground, creates an equivalent circuit.
3. The RJ45 shield should be attached directly to chassis ground.



+3.3V Power Supply Connections:

1. The digital supply (VDD33IO) pins on the LAN89730 QFN are 25, 35, 48, 51 & 52. They require a connection to +3.3V.
2. Each power pin should have one .01 μF (or smaller) capacitor to decouple the LAN89730. The capacitor size should be SMD_0603 or smaller.
3. The analog supply (VDD33A) pins on the LAN89730 QFN are 4, 8 & 15. They require a connection to +3.3V through a ferrite bead. Be sure to place bulk capacitance on each side of the ferrite bead.
4. Each VDD33A pin should have one .01 μF (or smaller) capacitor to decouple the LAN89730. The capacitor size should be SMD_0603 or smaller.

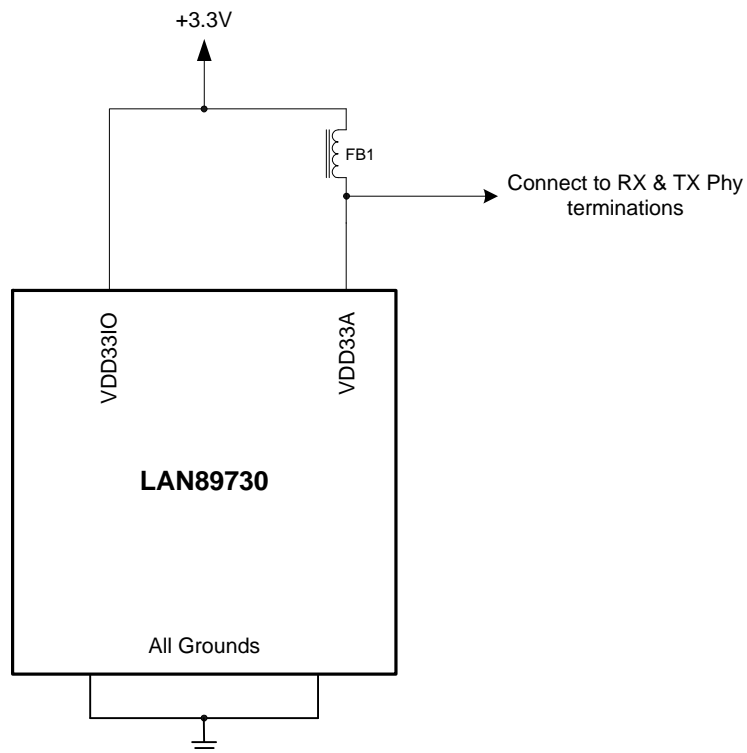


Figure 3 - +3.3V Power Supply Connections

VDD12CORE:

1. VDD12CORE (pins 21 & 50), these two pins are used to provide bypassing for the +1.2V core regulator. Each pin requires a 0.01 μF decoupling capacitor. Each capacitor should be located as close as possible to its pin without using vias. In addition, pin 50 requires a bulk capacitor placed as close as possible to pin 50. The bulk capacitor must have a value of at least 1.0 μF , and have an ESR (equivalent series resistance) of no more than 0.1 Ω . SMSC recommends a very low ESR ceramic capacitor for design stability. Other values, tolerances & characteristics are not recommended.

Caution: This +1.2V supply is for internal logic only and LAN89730 use only. **Do Not** power other external circuits or devices with this supply.

2. VDD12PLL (pin 9), this pin supplies power for the core PLL and the Ethernet Phy. This pin must be connected to VDD12CORE through a ferrite bead. Be sure to place bulk capacitance on each side of the ferrite bead.
3. The VDD12PLL pin should have one .01 μF (or smaller) capacitor to decouple the LAN89730. The capacitor size should be SMD_0603 or smaller.
4. VDD12USBPLL (pin 17), this pin supplies power for the HSIC USB Phy's PLL. This pin must be connected to VDD12CORE through a second ferrite bead. Be sure to place bulk capacitance on each side of the ferrite bead.
5. The VDD12USBPLL pin should have one .01 μF (or smaller) capacitor to decouple the LAN89730. The capacitor size should be SMD_0603 or smaller.
6. VDD12A (pin 12), this pin supplies power for the HSIC USB Phy. This pin must be connected to VDD12CORE through a third ferrite bead. Be sure to place bulk capacitance on each side of the ferrite bead.
7. The VDD12A pin should have one .01 μF (or smaller) capacitor to decouple the LAN89730. The capacitor size should be SMD_0603 or smaller.



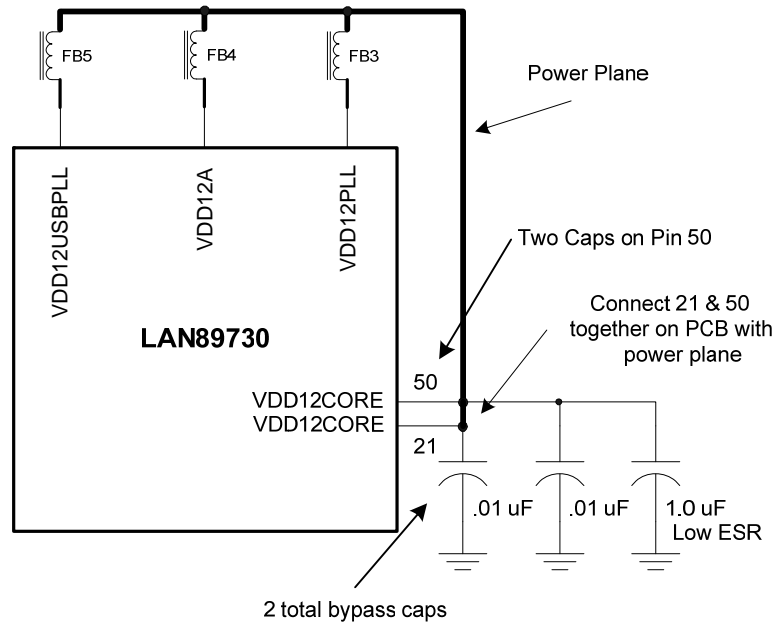


Figure 4 - LAN89730 +1.2V Power Connections

Ground Connections:

1. All grounds, the digital ground pins (GND), the core ground pins (GND_CORE) and the analog ground pins (VSS_A) on the LAN89730 QFN, are all connected internally to the exposed die paddle ground (VSS). The EDP Ground pad on the underside of the LAN89730 must be connected directly to a solid, contiguous digital ground plane.
2. On the PCB, we recommend one Digital Ground. We do not recommend running separate ground planes for any of our LAN products.

Crystal Connections:

1. A 25.000 MHz crystal must be used with the LAN89730 QFN. For exact specifications and tolerances refer to the latest revision LAN89730 data sheet.
2. XI (pin 18) on the LAN89730 QFN is the clock circuit input. This pin requires a 15 – 33 pF capacitor to digital ground. One side of the crystal connects to this pin.
3. XO (pin 19) on the LAN89730 QFN is the clock circuit output. This pin requires a matching 15 – 33 pF capacitor to ground and the other side of the crystal.
4. Since every system design is unique, the capacitor values are system dependant. The PCB design, the crystal selected, the layout and the type of caps selected all contribute to the characteristics of this circuit. Once the board is complete and operational, it is up to the system engineer to analyze this circuit in a lab environment. The system engineer should verify the frequency, the stability and the voltage level of the circuit to guarantee that the circuit meets all design criteria as put forth in the data sheet.
5. For proper operation, the additional external 1.0M Ω resistor across the crystal is no longer required. The necessary resistance has been designed-in internally on the LAN89730 QFN.
6. In order to guarantee IEEE compliancy over the entire temperature range of operation, the crystal / oscillator used in conjunction with the LAN89730 must be rated for Automotive Temperature use.

EEPROM Interface:

1. EECS (pin 30) on the LAN89730 QFN connects to the external EEPROM's CS pin.
2. EECLK (pin 29) on the LAN89730 QFN connects to the external EEPROM's serial clock pin.
3. EEDI (pin 32) on the LAN89730 QFN connects to the external EEPROM's Data Out pin.
4. EEDO (pin 31) on the LAN89730 QFN connects to the external EEPROM's Data In pin.
5. Be sure to select a 3-wire style 2K/4K EEPROM that is organized for 256/512 x 8-bit operation.
6. In order to guarantee IEEE compliancy over the entire temperature range of operation, the EEPROM used in conjunction with the LAN89730 must be rated for Automotive Temperature use.

EXRES Resistor:

1. EXRES (pin 7) on the LAN89730 QFN should connect to digital ground through a 12.0K Ω resistor with a tolerance of 1.0%. This pin is used to set-up critical bias currents for the embedded 10/100 Ethernet Physical device.



USBBIAS Resistor:

1. USBBIAS (pin 16) on the LAN89730 QFN should connect to digital ground through a 12.0K Ω resistor with a tolerance of 1.0%. This pin is used to set-up critical bias currents for the embedded USB Physical device.

Required External Pull-ups/Pull-downs:

1. GPIO0 (pin 46) A pull-up resistor would be required if this pin is programmed as an Open Drain Output.
2. GPIO1 (pin 23) A pull-up resistor would be required if this pin is programmed as an Open Drain Output.
3. GPIO2 (pin 22) A pull-up resistor would be required if this pin is programmed as an Open Drain Output.
4. GPIO3 (pin 45) A pull-up resistor would be required if this pin is programmed as an Open Drain Output.
5. GPIO4 (pin 56) A pull-up resistor would be required if this pin is programmed as an Open Drain Output.
6. GPIO5 (pin 55) A pull-up resistor would be required if this pin is programmed as an Open Drain Output.
7. GPIO6 (pin 54) A pull-up resistor would be required if this pin is programmed as an Open Drain Output.
8. GPIO7 (pin 53) A pull-up resistor would be required if this pin is programmed as an Open Drain Output.
9. GPIO8 (pin 26) A pull-up resistor would be required if this pin is programmed as an Open Drain Output.
10. GPIO9 (pin 27) A pull-up resistor would be required if this pin is programmed as an Open Drain Output.
11. GPIO10 (pin 28) A pull-up resistor would be required if this pin is programmed as an Open Drain Output.



MII Interface:

- When utilizing either an external MII Phy or an MII Connector, the following table indicates the proper connections for the 17 signals.

From:	Connects To:	
	MII Physical Device	MII Connector
LAN89730 QFN		
RXD0 (pin 36)	RXD<0>	RXD<0> (contact 7)
RXD1 (pin 38)	RXD<1>	RXD<1> (contact 6)
RXD2 (pin 39)	RXD<2>	RXD<2> (contact 5)
RXD3 (pin 40)	RXD<3>	RXD<3> (contact 4)
RX_DV (pin 42)	RX_DV	RX_DV (contact 8)
RX_ER (pin 44)	RX_ER	RX_ER (contact 10)
RX_CLK (pin 41)	RX_CLK	RX_CLK (contact 9)
TXD0 (pin 56)	TXD<0>	TXD<0> (contact 14)
TXD1 (pin 55)	TXD<1>	TXD<1> (contact 15)
TXD2 (pin 54)	TXD<2>	TXD<2> (contact 16)
TXD3 (pin 53)	TXD<3>	TXD<3> (contact 17)
TX_EN (pin 43)	TX_EN	TX_EN (contact 13)
TX_CLK (pin 47)	TX_CLK	TX_CLK (contact 12)
TX_ER	TX_ER	TX_ER (contact 11)
CRS (pin 45)	CRS	CRS (contact 19)
COL (pin 46)	COL	COL (contact 18)
MDIO (pin 23)	MDIO	MDIO (contact 2)
MDC (pin 22)	MDC	MDC (contact 3)

- If the MII interface is not used by the system, do not terminate on the board level. These pins have the proper internal terminations and should be left as no-connects.



HSIC Interface:

1. HSIC_DATA (pin 10), this pin is the Bi-directional Double Data Rate (DDR) data signal that is synchronous to the HSIC_STROBE signal as defined in the [High-Speed Inter-Chip USB Specification, Version 1.0](#).
2. HSIC_STROBE (pin 11), this pin is the Bi-directional data strobe signal as defined in the [High-Speed Inter-Chip USB Specification, Version 1.0](#).
3. The HSIC_DATA and HSIC_STROBE pin timing adheres to the HSIC 1.0 specification. Refer to the High-Speed Interchip USB Electrical Specification Revision 1.0 (09-23-07) and USB HSIC ECN for detailed USB timing information.
4. SLEW_TUNE (pin 20), this pin applies a 30% slew rate boost to the HSIC_DATA and HSIC_STROBE pins when driven high. This pin has a weak internal pull-down and can be driven high with an external 10.0K Ω resistor to VDD33IO.
5. The HSIC interface is only recommended for intra-board interconnect. Connectors and cables are not recommended. The connection should be point-to-point.



Configuration Straps:

1. All configuration strap values are latched in on Power-On Reset and System Reset. For more detailed information of each bit and functionality, consult the latest version of the LAN89730 data sheet.
2. AUTOMDIX_EN (pin 31), this pin determines the default Auto MDIX setting. The settings are as follows:

0 = Auto MDIX is disabled
1 = Auto MDIX is enabled

See the latest version of the LAN89730 data sheet for complete details. This pin has a weak internal pull-up and can be driven low with an external 10.0K Ω resistor to digital ground.

3. PORT_SWAP (pin 54), this pin determines the mapping of the HSIC pins. The settings are as follows:

0 = HSIC_DATA & HSIC_STROBE functionality is not swapped
1 = HSIC_DATA & HSIC_STROBE functionality is swapped

See the latest version of the LAN89730 data sheet for complete details. This pin has a weak internal pull-down and can be driven high with an external 10.0K Ω resistor to VDD33IO.

4. PHY_SEL (pin 34), this pin determines whether the internal Ethernet Phy is enabled or the LAN89730 will be used with an external Ethernet Phy. The settings are as follows:

0 = Internal Phy is used
1 = External Phy is used

See the latest version of the LAN89730 data sheet for complete details. This pin has a weak internal pull-down and can be driven high with an external 10.0K Ω resistor to VDD33IO.

5. RMT_WKP (pin 55), this pin determines the default descriptor values for remote wakeup functionality. This strap is overridden by the EEPROM. The settings are as follows:

0 = Remote wakeup is not supported
1 = Remote wakeup is supported

See the latest version of the LAN89730 data sheet for complete details. This pin has a weak internal pull-down and can be driven high with an external 10.0K Ω resistor to VDD33IO.

6. EEP_DISABLE (pin 56), this pin disables autoloading of the EEPROM contents. The assertion of this strap does not prevent register access to the EEPROM. The settings are as follows:

0 = EEPROM is recognized if present
1 = EEPROM is not recognized even if it is present

See the latest version of the LAN89730 data sheet for complete details. This pin has a weak internal pull-down and can be driven high with an external 10.0K Ω resistor to VDD33IO.



7. 50DRIVER_EN (pin 53), this pin determines the output impedance for the HSIC_DATA and HSIC_STROBE drivers. The settings are as follows:

0 = 40 ohm output impedance
1 = 50 ohm output impedance

See the latest version of the LAN89730 data sheet for complete details. This pin has a weak internal pull-up and can be driven low with an external 10.0K Ω resistor to digital ground. Most applications will use 50 ohms output impedance.

8. CORE_REG_EN (pin 49), this pin enables / disables the internal core logic voltage regulator. The settings are as follows:

0 = Tied to VSS, the core regulator is disabled
1 = Tied to +3.3V, the core regulator is enabled

See the latest version of the LAN89730 data sheet for complete details. This pin has no internal terminations and must be terminated. When the internal regulator is disabled, an external +1.2V power supply must be used.



Miscellaneous:

1. nRESET (pin 24), this pin is an active-low reset input. This signal resets all logic and registers within the LAN89730. This signal is pulled high with a weak internal pull-up resistor. If nRESET is left unconnected the LAN89730 will rely on its internal power-on reset circuitry.
2. nPHY_INT (pin 1), this pin is configured as either an output or input depending upon the Ethernet Phy configuration. When using the internal Ethernet Phy, this pin is configured as an output and indicates the Phy interrupt status. This signal is an active low indication.

When using an external Ethernet Phy with the LAN89730, this pin is configured as an input to the internal MAC and indicates the Phy interrupt status. This signal is an active low indication. When in this mode, this input is configured with a weak internal pull-up.

3. nPHY_RST (pin 37), this pin is configured as an output when the LAN89730 is in external Ethernet Phy mode. This signal is an active low indication. This signal should be routed to the nRESET input of the external Phy to reset all registers.
4. nFDX_LED (pin 26), nLNKA_LED (pin 27) & nSPD_LED (pin 28), can be programmed via register settings to display various Ethernet activity such as Speed, Link & Duplex Status. See the latest version of the LAN89730 data sheet for complete details. These pins have weak internal pull-ups.
5. The LAN89730 has an IEEE 1149.1 compliant JTAG Boundary Scan interface. This test interface can be utilized to accomplish board level testing to ensure system functionality and board manufacturability. For details, see the LAN89730 data sheet.
6. TEST2 (pin 13), this pin must be tied directly to +3.3V in order to ensure proper operation.
7. TEST1 (pin 33), this pin must be tied directly to digital ground in order to ensure proper operation.
8. Incorporate a large SMD resistor (SMD_1210) to connect the chassis ground to the digital ground. This will allow some flexibility at EMI testing for different grounding options. Leave the resistor out, the two grounds are separate. Short them together with a zero ohm resistor. Short them together with a cap or a ferrite bead for best performance.
9. Be sure to incorporate enough bulk capacitors (4.7 - 22 μ F caps) for each power plane.
10. In order to guarantee IEEE / AEC-Q100 compliancy over the entire temperature range of operation, all components used in the customer's application must be rated for Automotive Temperature use. Processors, crystals, oscillators, magnetics and all integrated circuits must be rated properly to avoid operational inconsistencies.



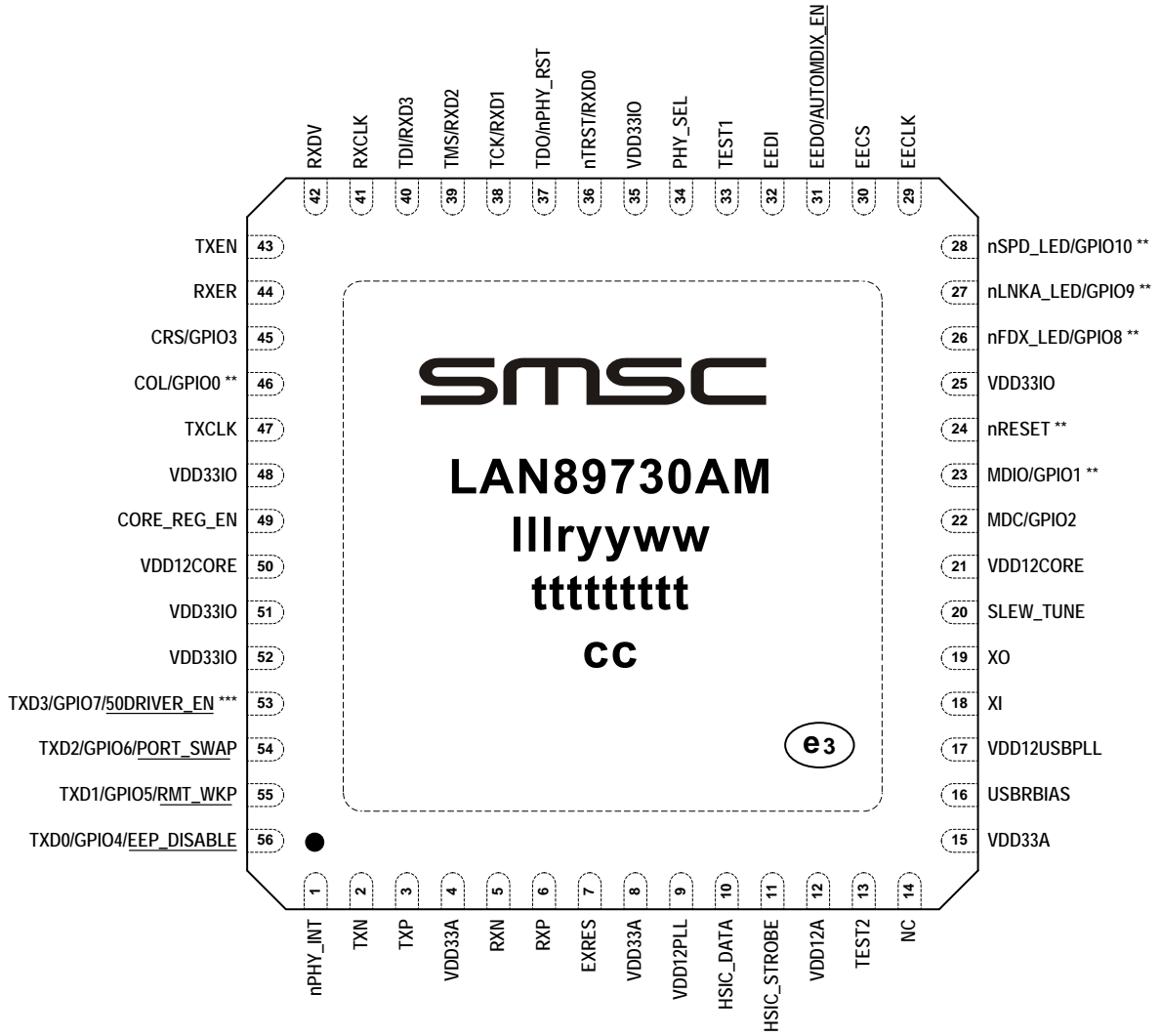
LAN89730 QFN QuickCheck Pinout Table:

Use the following table to check the LAN89730 QFN shape in your schematic.

LAN89730 QFN			
Pin No.	Pin Name	Pin No.	Pin Name
1	nPHY_INT	29	EECLK
2	TXN	30	EECS
3	TXP	31	EEDO / AUTOMDIX_EN
4	VDD33A	32	EEDI
5	RXN	33	TEST1
6	RXP	34	PHY_SEL
7	EXRES	35	VDD33IO
8	VDD33A	36	nTRST / RXD0
9	VDD12PLL	37	TDO / nPHY_RST
10	HSIC_DATA	38	TCK / RXD1
11	HSIC_STROBE	39	TMS / RXD2
12	VDD12A	40	TDI / RXD3
13	TEST2	41	RXCLK
14	NC	42	RXDV
15	VDD33A	43	TXEN
16	USBRBIAS	44	RXER
17	VDD12USBPLL	45	CRS / GPIO3
18	XI	46	COL / GPIO0
19	XO	47	TXCLK
20	SLEW_TUNE	48	VDD33IO
21	VDD12CORE	49	CORE_REG_EN
22	MDC / GPIO2	50	VDD12CORE
23	MDIO / GPIO1	51	VDD33IO
24	nRESET	52	VDD33IO
25	VDD33IO	53	TXD3 / GPIO7 / 50DRIVER_EN
26	nFDX_LED / GPIO8	54	TXD2 / GPIO6 / PORT_SWAP
27	nLNKA_LED / GPIO9	55	TXD1 / GPIO5 / RMT_WKP
28	nSPD_LED / GPIO10	56	TXD0 / GPIO4 / EEP_DISABLE
57		EDP Ground Connection Exposed Die Paddle Ground Pad on Bottom of Package	



LAN89730 QFN Package Drawing:



Reference Material:

1. SMSC LAN89730 Data Sheet; check web site for latest revision.
2. SMSC LAN89730 CEB Schematic, Assembly No. 6660; check web site for latest revision.
3. SMSC LAN89730 CEB PCB, Assembly No. 6660; order PCB from web site.
4. SMSC LAN89730 CEB PCB Bill of Materials, Assembly No. 6660; check web site for latest revision.
5. CEB stands for Customer Evaluation Board.
6. SMSC LAN89730 Reference Design, check web site for latest revision.
7. SMSC Reference Designs are schematics only; there are no associated PCBs.
8. For Qualified / Suggested Magnetics, use these two links to the SMSC LANCheck website:

https://www2.smisc.com/mkt/web_lancheck.nsf/MagList?OpenForm

https://www2.smisc.com/mkt/web_lancheck.nsf/MagCheck?OpenForm

